HARRIS SEMICONDUCTOR

CD74FCT373T, CD74FCT533T, CD74FCT573T, CD74FCT2373T, CD74FCT2573T

December 1996

Fast CMOS Octal Transparent Latches

Features

- **Advanced 0.8 micron CMOS Technology**
- **Pin Compatible with Bipolar FAST™ Series at a Higher Speed and Lower Power Consumption**
- **25Ω Series Resistor on All Outputs (CD74FCT2373T, CD74FCT2573T Only)**
- **TTL Input and Output Levels**
- **Low Ground Bounce Outputs**
- **Extremely Low Static Power**
- **Hysteresis on All Inputs**

Description

These devices are 8-bit wide octal transparent latches designed with three-state outputs and are intended for bus oriented applications. When Latch Enable (LE) is HIGH, the flip-flops appear transparent to the data. The data that meets the set-up time when LE is LOW is latched. When $\overline{OE}$ is HIGH, the bus output is in the high impedance state.

The CD74FCT2XXX device has a built-in 25Ω series resistor on all outputs to reduce noise due to reflections, thus eliminating the need for an external terminating resistor.

Ordering Information

PART NUMBER	TEMP. RANGE (^{o}C)	PACKAGE	PKG. NO.
CD74FCT373ATM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT373ATQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT373CTM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT373CTQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT373DTM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT373DTQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT373TM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT373TQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT533ATM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT533ATQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT533CTM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT533CTQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT533TM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT533TQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT573ATM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT573ATQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT573CTM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT573CTQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT573DTM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT573DTQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT573TM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT573TQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT2373ATM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT2373ATQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT2373CTM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT2373CTQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT2373TM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT2373TQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT2573ATM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT2573ATQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT2573CTM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT2573CTQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT2573TM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT2573TQM	-40 to 85	20 Ld QSOP	M20.15-P

NOTE: QSOP is commonly known as SSOP.

When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.

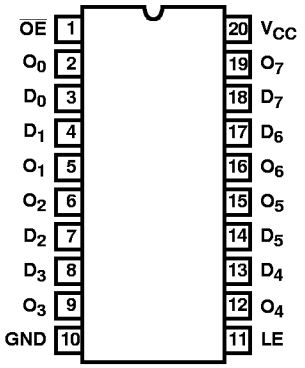
CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper IC Handling Procedures.

FAST™ is a trademark of Fairchild Semiconductor.

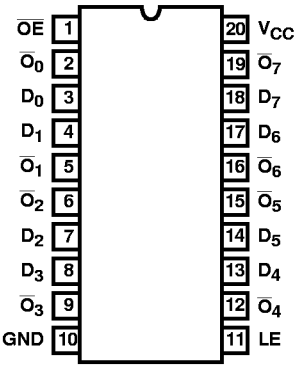
File Number **4170.2**

Pinouts

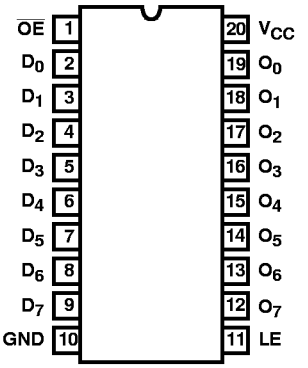
CD74FCT373T, CD74FCT2373T
(QSOP, SOIC)
TOP VIEW



CD74FCT533T
(QSOP, SOIC)
TOP VIEW

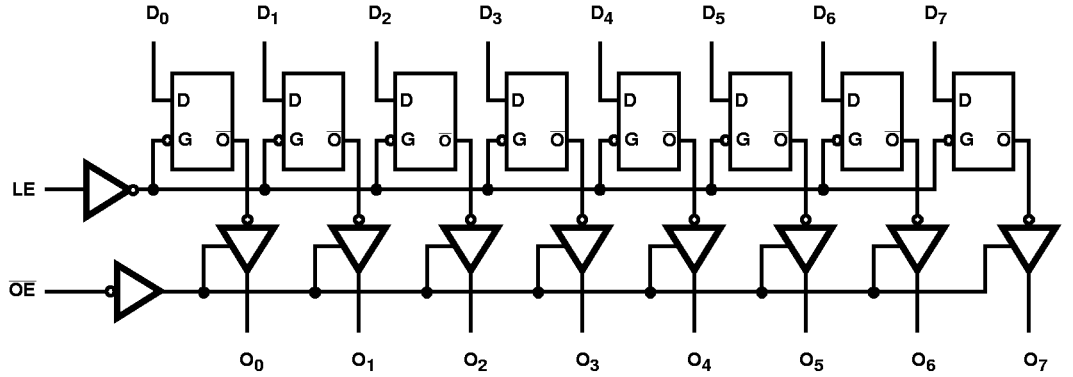


CD74FCT573T, CD74FCT2573T
(QSOP, SOIC)
TOP VIEW

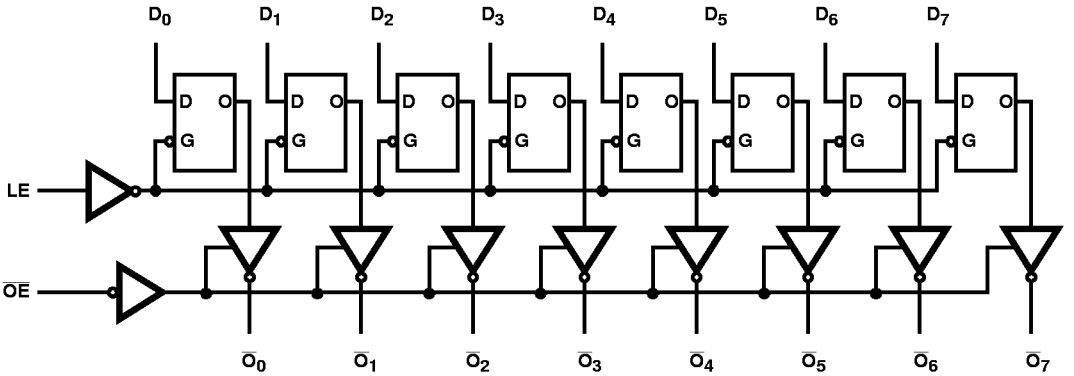


Functional Block Diagrams

CD74FCT373T, CD74FCT2373T, CD74FCT573, CD74FCT2573T



CD74FCT533T



TRUTH TABLE (NOTE 1)

INPUTS			OUTPUTS
D_N	LE	$\overline{OE}$	$\overline{O}_N$
CD74FCT533T			
H	H	L	L
L	H	L	H
X	X	H	Z

TRUTH TABLE (NOTE 1)

INPUTS			OUTPUTS
D_N	LE	$\overline{OE}$	O_N
CD74FCT373T, CD74FCT573T, CD74FCT2373T, CD74FCT2573T			
H	H	L	H
L	H	L	L
X	X	H	Z

NOTE:

1. H = High Voltage Level
   L = Low Voltage Level
   X = Don't Care
   Z = High Impedance

Pin Descriptions

PIN NAME	DESCRIPTION
$\overline{OE}$	Output Enable Input (Active LOW)
LE	Latch Enable Input (Active HIGH)
D_0-D_7	Data Inputs
O_0-O_7	Three-State Outputs
$\overline{O}_0$-$\overline{O}_7$	Complementary Three-State Outputs
GND	Ground
V_{CC}	Power

Absolute Maximum Ratings

DC Input Voltage . . . . . -0.5V to 7.0V
DC Output Current 120mA

Operating Conditions

Operating Temperature Range . . . . . $-40^{o}C$ to $85^{o}C$
Supply Voltage to Ground Potential
Inputs and V_{CC} Only . . . . . -0.5V to 7.0V
Supply Voltage to Ground Potential
Outputs and D/O Only. . . . . -0.5V to 7.0V

Thermal Information

Thermal Resistance (Typical, Note 2)	θ_{JA} ($^{o}C/W$)
SOIC Package	87
QSOP Package	110

Maximum Junction Temperature . . . . . $150^{o}C$
Maximum Storage Temperature Range . . . . . $-65^{o}C$ to $150^{o}C$
Maximum Lead Temperature (Soldering 10s) . . . . . $300^{o}C$
(Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

2. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications

PARAMETERS	SYMBOL	(NOTE 3) TEST CONDITIONS		MIN	(NOTE 4) TYP	MAX	UNITS
DC ELECTRICAL SPECIFICATIONS Over the Operating Range, $T_A = -40^{o}C$ to $85^{o}C$, $V_{CC} = 5.0V \pm 5\%$							
Output HIGH Voltage	V_{OH}	V_{CC} = Min, $V_{IN} = V_{IH}$ or V_{IL}	I_{OH} = -15.0mA	2.4	3.0	-	V
Output LOW Voltage	V_{OL}	V_{CC} = Min, $V_{IN} = V_{IH}$ or V_{IL}	I_{OL} = 64mA	-	0.3	0.50	V
Output LOW Voltage	V_{OL}	V_{CC} = Min, $V_{IN} = V_{IH}$ or V_{IL}	I_{OL} = 12mA (25Ω Series)	-	0.3	0.50	V
Input HIGH Voltage	V_{IH}	Guaranteed Logic HIGH Level		2.0	-	-	V
Input LOW Voltage	V_{IL}	Guaranteed Logic LOW Level		-	-	0.8	V
Input HIGH Current	I_{IH}	V_{CC} = Max	$V_{IN} = V_{CC}$	-	-	1	µA
Input LOW Current	I_{IL}	V_{CC} = Max	V_{IN} = GND	-	-	-1	µA
High Impedance Output Current	I_{OZH}	V_{CC} = Max	V_{OUT} = 2.7V	-	-	1	µA
	I_{OZL}		V_{OUT} = 0.5V	-	-	-1	µA
Clamp Diode Voltage	V_{IK}	V_{CC} = Min, I_{IN} = -18mA		-	-0.7	-1.2	V
Short Circuit Current	I_{OS}	V_{CC} = Max (Note 5), V_{OUT} = GND		-60	-120	-	mA
Power Down Disable	I_{OFF}	V_{CC} = GND, V_{OUT} = 4.5V		-	-	100	µA
Input Hysteresis	V_H			-	200	-	mV
CAPACITANCE $T_A = 25^{o}C$, f = 1MHz							
Input Capacitance (Note 6)	C_{IN}	V_{IN} = 0V		-	6	10	pF
Output Capacitance (Note 6)	C_{OUT}	V_{OUT} = 0V		-	8	12	pF
POWER SUPPLY SPECIFICATIONS							
Quiescent Power Supply Current	I_{CC}	V_{CC} = Max	V_{IN} = GND or V_{CC}	-	0.1	500	µA
Supply Current per Input at TTL HIGH	ΔI_{CC}	V_{CC} = Max	V_{IN} = 3.4V (Note 7)	-	0.5	2.0	mA
Supply Current per Input per MHz (Note 8)	I_{CCD}	V_{CC} = Max, Outputs Open $\overline{OE}$ = GND; LE = V_{CC} One Input Toggling 50% Duty Cycle	$V_{IN} = V_{CC}$ V_{IN} = GND	-	0.15	0.25	mA/ MHz

Electrical Specifications (Continued)

PARAMETERS	SYMBOL	(NOTE 3) TEST CONDITIONS		MIN	(NOTE 4) TYP	MAX	UNITS
Total Power Supply Current (Note 10)	I_C	V_{CC} = Max, Outputs Open f_I = 10MHz, 50% Duty Cycle $\overline{OE}$ = GND; LE = V_{CC} One Bit toggling	$V_{IN} = V_{CC}$ V_{IN} = GND	-	1.5	3.0 (Note 9)	mA
			V_{IN} = 3.4V V_{IN} = GND	-	1.8	4.5 (Note 9)	mA
		V_{CC} = Max, Outputs Open f_I = 2.5MHz, 50% Duty Cycle $\overline{OE}$ = GND; LE = V_{CC} Eight Bits Toggling	$V_{IN} = V_{CC}$ V_{IN} = GND	-	3.0	6.0 (Note 9)	mA
			V_{IN} = 3.4V V_{IN} = GND	-	5.0	14.0 (Note 9)	mA

Switching Specifications Over Operating Range

PARAMETER	SYMBOL	(NOTE 11) TEST CONDITIONS	T		AT		CT		DT CD74FCT373T ONLY		UNITS
			(NOTE 12) MIN	MAX	(NOTE 12) MIN	MAX	(NOTE 12) MIN	MAX	(NOTE 12) MIN	MAX	
CD74FCT373T, CD74FCT2373T											
Propagation Delay D_N to O_N	t_{PLH}, t_{PHL}	C_L = 50pF R_L = 500Ω	1.5	8.0	1.5	5.2	1.5	4.2	1.5	3.8	ns
Propagation Delay LE to O_N	t_{PLH}, t_{PHL}		2.0	13.0	2.0	8.5	2.0	5.5	1.5	4.9	ns
Output Enable Time $\overline{OE}$ to O_N	t_{PZH}, t_{PZL}		1.5	12.0	1.5	6.5	1.5	5.5	1.5	5.5	ns
Output Disable Time (Note 13) $\overline{OE}$ to O_N	t_{PHZ}, t_{PLZ}		1.5	7.5	1.5	5.5	1.5	5.0	1.5	5.0	ns
Setup Time HIGH or LOW, D_N to LE	t_{SU}		2.0	-	2.0	-	2.0	-	2.0	-	ns
Hold Time HIGH or LOW, D_N to LE	t_H		1.5	-	1.5	-	1.5	-	1.5	-	ns
LE Pulse Width (Note 13) HIGH	t_W		6.0	-	5.0	-	5.0	-	4.0	-	ns
CD74FCT533T											
Propagation Delay D_N to O_N	t_{PLH}, t_{PHL}	C_L = 50pF R_L = 500Ω	1.5	10.0	1.5	5.2	1.5	4.2	-	-	ns
Propagation Delay LE to On	t_{PLH}, t_{PHL}		2.0	13.0	2.0	8.5	2.0	5.5			ns
Output Enable Time $\overline{OE}$ to O_N	t_{PZH}, t_{PZL}		1.5	11.0	1.5	6.5	1.5	5.5	-	-	ns
Output Disable Time (Note 13) $\overline{OE}$ to O_N	t_{PHZ}, t_{PLZ}		1.5	7.0	1.5	5.5	1.5	5.0			ns
Setup Time HIGH or LOW, D_N to LE	t_{SU}		2.0	-	2.0	-	2.0	-	-	-	ns
Hold Time HIGH or LOW, D_N to LE	t_H		1.5	-	1.5	-	1.5	-			ns
LE Pulse Width (Note 13) HIGH	t_W		6.0	-	5.0	-	5.0	-	-	-	ns

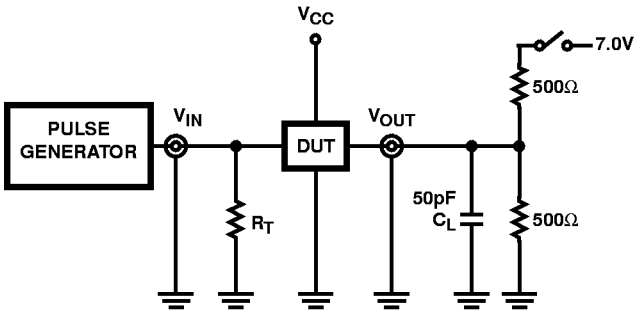
Switching Specifications Over Operating Range

PARAMETER	SYMBOL	(NOTE 11) TEST CONDITIONS	T (NOTE 12) MIN	T MAX	AT (NOTE 12) MIN	AT MAX	CT (NOTE 12) MIN	CT MAX	DT CD74FCT373T ONLY (NOTE 12) MIN	DT CD74FCT373T ONLY MAX	UNITS
CD74FCT573T, CD2573T											
Propagation Delay D_N to $\overline{O}_N$	t_{PLH}, t_{PHL}	C_L = 50pF R_L = 500Ω	1.5	8.0	1.5	5.2	1.5	4.2	1.5	3.8	ns
Propagation Delay LE to $\overline{O}n$	t_{PLH}, t_{PHL}		2.0	12.0	2.0	8.5	2.0	5.5	2.0	4.9	ns
Output Enable Time $\overline{OE}$ to O_N	t_{PZH}, t_{PZL}		1.5	9.5	1.5	6.5	1.5	5.5	1.5	5.5	ns
Output Disable Time (Note 13) $\overline{OE}$ to O_N	t_{PHZ}, t_{PLZ}		1.5	6.5	1.5	5.5	1.5	5.0	1.5	5.0	ns
Setup Time HIGH or LOW, D_N to LE	t_{SU}		2.0	-	2.0	-	2.0	-	1.5	-	ns
Hold Time HIGH or LOW, D_N to LE	t_H		1.5	-	1.5	-	1.5	-	1.0	-	ns
LE Pulse Width (Note 13) HIGH	t_W		6.0	-	5.0	-	5.0	-	3.0	-	ns

NOTES:

3. For conditions shown as Max or Min, use appropriate value specified under Electrical Characteristics for the applicable device type.
4. Typical values are at V_{CC} = 5.0V, 25°C ambient and maximum loading.
5. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
6. This parameter is determined by device characterization but is not production tested.
7. Per TTL driven input (V_{IN} = 3.4V); all other inputs at V_{CC} or GND.
8. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
9. Values for these conditions are examples of the Icc formula. These limits are guaranteed but not tested.
10. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
    $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_{CP}/2 + f_I N_I)$
    I_{CC} = Quiescent Current
    ΔI_{CC} = Power Supply Current for a TTL High Input (V_{IN} = 3.4V)
    D_H = Duty Cycle for TTL Inputs High
    N_T = Number of TTL Inputs at D_H
    I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
    f_{CP} = Clock Frequency for Register Devices (Zero for Non-Register Devices)
    f_I = Input Frequency
    N_I = Number of Inputs at f_I
    All currents are in milliamps and all frequencies are in megahertz.
11. See test circuit and wave forms.
12. Minimum limits are guaranteed but not tested on Propagation Delays.
13. This parameter is guaranteed but not production tested.c

Test Circuits and Waveforms



SWITCH POSITION

TEST	SWITCH
t_{PLZ}, t_{PZL}	Closed
t_{PHZ}, t_{PZH}, t_{PLH}, t_{PHL}	Open

DEFINITIONS:

C_L = Load capacitance, includes jig and probe capacitance.

R_T = Termination resistance, should be equal to Z_{OUT} of the Pulse Generator.

NOTE:

14. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; Z_{OUT} ≤ 50Ω; t_f, t_r ≤ 2.5ns.

FIGURE 1. TEST CIRCUIT

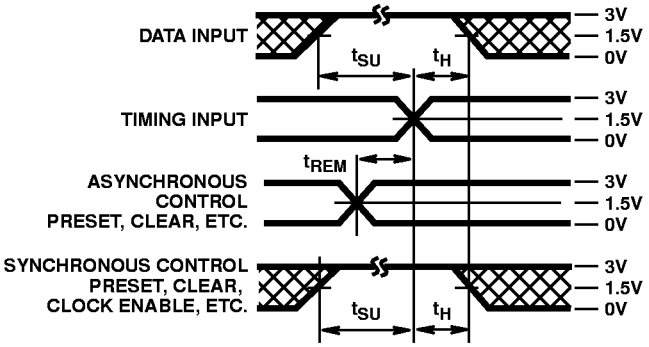


FIGURE 2. SETUP, HOLD, AND RELEASE TIMING

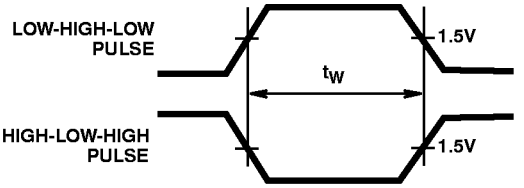


FIGURE 3. PULSE WIDTH

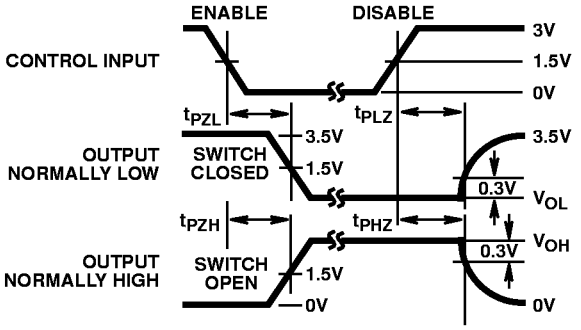


FIGURE 4. ENABLE AND DISABLE TIMING

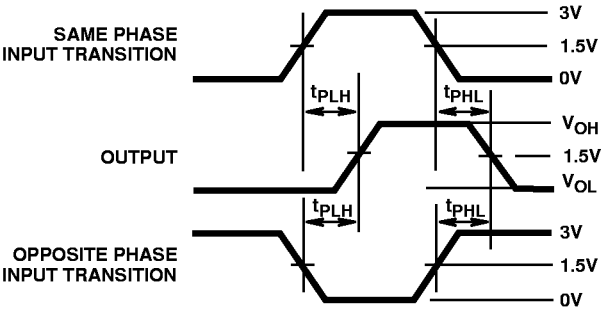
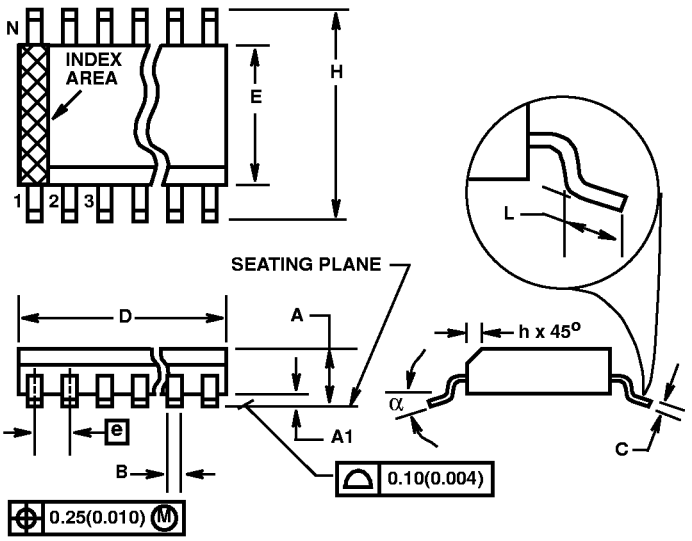


FIGURE 5. PROPAGATION DELAY

Small Outline Plastic Packages (SOIC)



M20.3-P

20 LEAD WIDE BODY SMALL OUTLINE PLASTIC PACKAGE

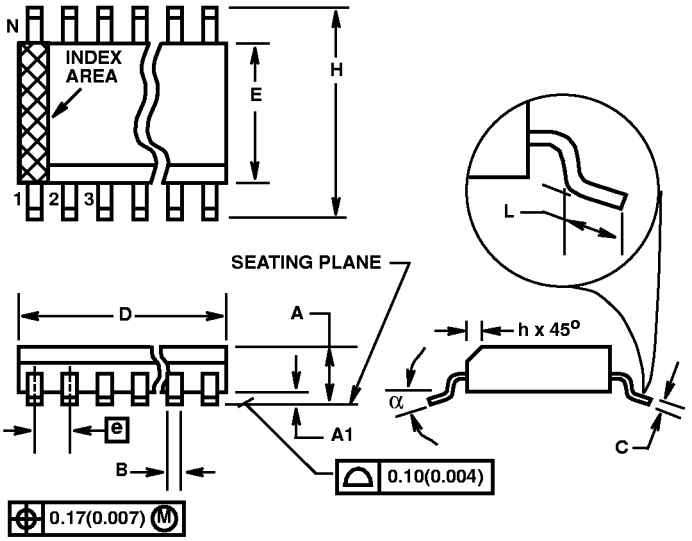
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.092	0.105	2.34	2.67	-
A1	0.004	0.012	0.102	0.302	-
B	0.013	0.020	0.330	0.508	-
C	0.009	0.011	0.229	0.279	-
D	0.496	0.512	12.60	13.00	1
E	0.291	0.299	7.39	7.59	2
e	0.050 BSC		1.27 BSC		-
H	0.401	0.411	10.18	10.44	-
h	0.010	0.029	0.254	0.737	-
L	0.016	0.050	0.41	1.27	3
N	20		20		4
α	0^o	8^o	0^o	8^o	-

Rev. 0 5/96

NOTES:

1. Dimension “D” does not include mold flash, protrusions or gate burrs.
2. Dimension “E” does not include interlead flash or protrusions.
3. “L” is the length of terminal for soldering to a substrate.
4. “N” is the number of terminal positions.
5. Terminal numbers are shown for reference only.
6. Controlling dimension: INCHES. Converted millimeter dimensions are not necessarily exact.

Shrink Small Outline Plastic Packages (SSOP/QSOP)



M20.15-P

20 LEAD SHRINK NARROW BODY SMALL OUTLINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.053	0.069	1.35	1.75	-
A1	0.007	0.011	0.178	0.279	-
B	0.008	0.012	0.203	0.305	-
C	0.007	0.010	0.178	0.254	-
D	0.337	0.344	8.56	8.74	1
E	0.149	0.157	3.78	3.99	2
e	0.025 BSC		0.635 BSC		-
H	0.228	0.244	5.79	6.20	-
h	0.015		0.38		-
L	0.016	0.050	0.41	1.27	3
N	20		20		4
α	0^o	8^o	0^o	8^o	-

Rev. 1 7/96

NOTES:

1. Dimension “D” does not include mold flash, protrusions or gate burrs.
2. Dimension “E” does not include interlead flash or protrusions.
3. “L” is the length of terminal for soldering to a substrate.
4. “N” is the number of terminal positions.
5. Terminal numbers are shown for reference only.
6. Controlling dimension: INCHES. Converted millimeter dimensions are not necessarily exact.